

L21: Entry 3 of 83

File: JPAB

Jan 19, 1999

PUB-NO: JP411012440A

DOCUMENT-IDENTIFIER: JP 11012440 A

TITLE: EPOXY RESIN COMPOSITION FOR SEALING SEMICONDUCTOR

PUBN-DATE: January 19, 1999

INVENTOR-INFORMATION:

NAME

COUNTRY

OTA, MASARU

ASSIGNEE-INFORMATION:

NAME

COUNTRY

SUMITOMO BAKELITE CO LTD

N/A

APPL-NO: JP09168738

APPL-DATE: June 25, 1997

INT-CL (IPC): C08L 63/00; C08G 59/62; C08K 3/00; C08K 5/54; H01L 23/29; H01L 23/31

ABSTRACT:

PROBLEM TO BE SOLVED: To obtain a composition excellent in adhesion to metals and organic substrate and in resistance to solder cracking by incorporating therein an epoxy resin, a phenolic resin curing agent, a curing accelerator, an inorganic filler, and an epoxy-silane coupling agent having a specific silanol group.

SOLUTION: The epoxy coupling agent is a compound as illustrated by the formula. In the formula, R is -CH₃ or -C₂H₅; a+b+c=3; a≥0; b>0; c≥0; b/(b+c)≥0.6. The epoxy resin represents all of monomers, oligomers and polymers having epoxy groups. It desirably includes epoxy resins of biphenyl-type, triphenylmethane-type, stilbene-type, etc. The phenolic resin curing agent desirably includes phenolic novolak resins, xylylene-modified phenolic resins, etc. As the curing accelerator, 1,8-diazabicyclo(5,4,0)undecene-7, triphenylphosphine, etc., are preferred. Preferable inorganic fillers include globular fused silica.

COPYRIGHT: (C)1999,JPO